T Number	11240	L Cooneb Mont	l DD	Time stems
L Number	Hits 22	Search Text ((immobile) with (chelat\$4))	DB USPAT;	Time stamp 2004/09/19 12:11
[-	22	(/INMHODITE) MICH (CHET9C54))	US-PGPUB;	2004/03/13 12:11
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	53	((immobile) same (chelat\$4))	USPAT;	2004/09/19 12:16
	, ,,	((IndioDiff) Ballio (Gliefact 1))	US-PGPUB;	2004,03,13 12:10
			EPO; JPO;	·
			DERWENT;	
			IBM TDB	
_	31	(((immobile) same (chelat\$4))) not	USPAT;	2004/09/19 12:19
		(((immobile) with (chelat\$4)))	US-PGPUB;	
		(,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	911	((immobile) and (chelat\$4))	USPĀT;	2004/09/19 13:32
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1			IBM_TDB	
-	2		USPAT;	2004/09/19 12:18
		((immobile adj particle\$1) and (chelat\$4))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		[, , , , , , , , , , , , , , , , , , ,	IBM_TDB	0004455455
-	193	(((immobile) and (chelat\$4))) and	USPAT;	2004/09/19 12:18
1		((immobile) and (chelating adj agent))	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
1_	172	((((immobile) and (chelat\$4))) and	USPAT;	2004/09/19 12:30
	1/2	(((immobile) and (chelating adj agent)))	US-PGPUB;	2004/09/19 12:30
		not ((((immobile) same (chelat\$4))) or	EPO; JPO;	
		(((immobile) with (chelat\$4))))	DERWENT;	
		(((Indiobelie) with (chiefactify)))	IBM TDB	
1_	686	(((immobile) and (chelat\$4))) not	USPAT;	2004/09/19 12:47
		(((((immobile) and (chelat\$4))) and	US-PGPUB;	2001, 00, 20 22111
	•	((immobile) and (chelating adj agent))) or	EPO; JPO;	
		(((immobile) same (chelat\$4))) or	DERWENT;	
		(((immobile) with (chelat\$4))))	IBM TDB	
-	45085	ibm.as.	USPAT;	2004/09/19 12:48
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	265	international-business-machines.as.	USPAT;	2004/09/19 15:29
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	48814	international adj business adj	USPAT;	2004/09/19 12:51
	40014	machines.as.	US-PGPUB;	2004/03/13 12:31
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	93874	ibm.as. or	USPAT;	2004/09/19 12:51
		international-business-machines.as. or	US-PGPUB;	
		(international adj business adj	EPO; JPO;	
		machines.as.)	DERWENT;	
			IBM TDB	
-	80	(ibm.as. or	USPAT;	2004/09/19 14:59
		international-business-machines.as. or	US-PGPUB;	
		(international adj business adj	EPO; JPO;	
		machines.as.)) and immobile	DERWENT;	
		· · ·	IBM_TDB	
-	171	(ibm.as. or	USPAT;	2004/09/19 13:32
		international-business-machines.as. or	US-PGPUB;	
		(international adj business adj	EPO; JPO;	
		machines.as.)) and chelat\$4	DERWENT;	~
			IBM_TDB	<u> </u>

-	4	((ibm.as. or	USPAT;	2004/09/19 12:52
		international-business-machines.as. or	US-PGPUB;	
		(international adj business adj	EPO; JPO;	
]	machines.as.)) and immobile) and ((ibm.as.	DERWENT;	
		or international-business-machines.as. or (international adj business adj	IBM_TDB	
		machines.as.)) and chelat\$4)		
! _	171	1 ' '	USPAT;	2004/09/19 13:12
	1/1	international-business-machines.as. or	US-PGPUB;	2004/03/13 13:12
		(international adj business adj	EPO; JPO;	
		machines.as.)) and chelat\$4) not	DERWENT;	
		((((174/260) or (174/256) or (174/52.2) or	IBM TDB	
		(264/272.11) or (438/126) or (438/127) or	-	
		(257/778) or (257/779) or (257/772) or		
		(257/789) or (257/780) or (257/787) or	1	
		(257/788) or (257/795) or		
		(257/632)).CCLS.) and ((immobile) and		
	1000	(chelat\$4)))		00011001101
-	18685	immobile	USPAT;	2004/09/19 17:29
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	104966	chelat\$4	USPAT;	2004/09/19 13:32
1	104500	011014071	US-PGPUB;	2004/05/15 15.52
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1906629	(chip) or (wafer) or (ic) or (integrated	USPAT;	2004/09/19 13:37
		adj circuit) or (semiconductor adj device)	US-PGPUB;	
		or (electronic adj component) or	EPO; JPO;	
ì		(electroinc adj device) or (printed adj	DERWENT;	
ŀ	i	circuit) or (printed adj wiring) or	IBM_TDB	
	105	(circuit adj board)	1100000-	2004/00/10 13:40
-	105	· · · · · · · · · · · · · · · · · · ·	USPAT;	2004/09/19 13:48
		(wafer) or (ic) or (integrated adj circuit) or (semiconductor adj device) or	US-PGPUB; EPO; JPO;	
		(electronic adj component) or (electroinc	DERWENT;	
		adj device) or (printed adj circuit) or	IBM TDB	
i		(printed adj wiring) or (circuit adj		
		board))		
-	1401		USPAT	2004/09/19 14:04
		(integrated adj circuit) or (semiconductor		
		adj device) or (electronic adj component)		
		or (electroinc adj device) or (printed adj		
		circuit) or (printed adj wiring) or		
_	6300	(circuit adj board)) chelat\$4 and ((chip) or (wafer) or (ic) or	USPAT	2004/09/27 11:59
	0300	(integrated adj circuit) or (semiconductor	OSEKI	2004/03/2/ 11:39
		adj device) or (electronic adj component)		
}		or (electroinc adj device) or (printed adj		
]		circuit) or (printed adj wiring) or		
		(circuit adj board))		
-	53	(======= , == , (==== <u>F</u> , == , =====, == ,==,	USPAT	2004/09/19 14:16
		or (integrated adj circuit) or		
		(semiconductor adj device) or (electronic		
		adj component) or (electroinc adj device)		
		or (printed adj circuit) or (printed adj wiring) or (circuit adj board))) and		
		(chelat\$4 and ((chip) or (wafer) or (ic)		
		or (integrated adj circuit) or		
		(semiconductor adj device) or (electronic		
[adj component) or (electroinc adj device)		
		or (printed adj circuit) or (printed adj		İ
		wiring) or (circuit adj board)))		
-	1137	chelat\$4 and (174/\$.ccls. or 29/\$.ccls. or	USPAT	2004/09/19 14:49
		257/\$.ccls. or 361/\$.ccls.)		
-	2	(chelat\$4 and (174/\$.ccls. or 29/\$.ccls.	USPAT	2004/09/19 14:58
		or 257/\$.ccls. or 361/\$.ccls.)) and		
L		immobile		

-	14	<pre>(composition) with (immobile) with (chelat\$ or complex\$4)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/19 17:44
-	747	<pre>(chelat\$4 and ((chip) or (wafer) or (ic) or (integrated adj circuit) or (semiconductor adj device) or (electronic adj component) or (electroinc adj device)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/19 15:31
		or (printed adj circuit) or (printed adj wiring) or (circuit adj board))) and (174/\$.ccls. or 29/\$.ccls. or 257/\$.ccls. or 361/\$.ccls.)	IBM_TDB	
-	74	((chelat\$4 and ((chip) or (wafer) or (ic) or (integrated adj circuit) or (semiconductor adj device) or (electronic adj component) or (electroinc adj device) or (printed adj circuit) or (printed adj wiring) or (circuit adj board))) and (174/\$.ccls. or 29/\$.ccls. or 257/\$.ccls. or 361/\$.ccls.)) and (high adj molecular	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 16:04
-	28	adj weight) immobile adj particle\$	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/19 17:29
-	42	<pre>(composition) same (immobile) same (chelat\$ or complex\$4)</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/19 17:45
-	28	<pre>((composition) same (immobile) same (chelat\$ or complex\$4)) not ((composition) with (immobile) with (chelat\$ or complex\$4))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/19 17:48
26	6564	chelating adj agent	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 10:48
- 11	1884	<pre>(chelating adj agent) or (immobile adj particle\$1)</pre>	USPĀT	2004/09/24 10:51
-	0	<pre>(chelating adj agent) and (immobile adj particle\$1)</pre>	USPAT	2004/09/24 10:51
-	28	immobile adj particle\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 15:23
-	746	<pre>(composition) with (metal adj ion\$1) with (chelat\$4)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/24 17:37
-	2	<pre>(composition) with (metal adj ion\$1) with (chelat\$4) with (Immobile adj particle\$1)</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/24 17:39
-	3	<pre>(composition) with (metal adj ion\$1) with (chelat\$4) with (Immobile)</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 17:44
-	0	("4and(chelat\$1)and(particle\$1)").PN. (("4707453").PN.) and (chelat\$1) and	USPAT USPAT	2004/09/24 17:46 2004/09/24 17:50
-	62	<pre>(particle\$1) ((composition) with (metal adj ion\$1) with (chelat\$4)) and (package)</pre>	USPAT	2004/09/24 17:51

_	1	((("4707453").PN.) and (chelat\$1) and	USPAT	2004/09/24 18:04
	,	(particle\$1)) and (package)	110022	2004/00/04 10:05
_	$\frac{1}{3}$	(particle\$1 adj chelat\$4) and package (particle\$1 adj chelat\$4) and package	USPAT USPAT	2004/09/24 18:05 2004/09/24 18:17
1 _	5	(particle\$1 adj chelat\$4) and package	USPAT;	2004/09/24 18:17
		(partitioner adj enclativi) and package	US-PGPUB	2004/03/24 10:07
_	6	(particle\$1 adj chelat\$4) and package	USPAT;	2004/09/24 18:14
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	
-	0	1 ,, ,, , ,	USPAT	2004/09/24 18:17
	0	chelat\$4)	USPAT	2004/00/24 10:17
<u>-</u>	1	(("6711423").PN.) and (immobile) (("6711423").PN.) and (chelat\$4)	USPAT	2004/09/24 18:17 2004/09/24 18:20
_	4540		USPAT;	2004/09/24 16:20
		or ethylenediamine or oxylate)	US-PGPUB	2001,03,20 10112
-	587	((chelat\$4) with (epta or ethylenediamine	USPAT;	2004/09/25 16:46
		or ethylenediamine or oxylate)) and	US-PGPUB	
		(electronic adj device or integrated adj		
		circuit or package or printed adj circuit		
		adj board or printed adj wiring adj board		
		or semiconductor adj device or semiconductor adj package)		
_	156		USPAT;	2004/09/25 16:46
		or ethylenediamine or oxylate)) and	US-PGPUB	
	,	(immobile)		
	10	(((chelat\$4) with (epta or ethylenediamine	USPAT;	2004/09/25 16:54
		or ethylenediamine or oxylate)) and	US-PGPUB	
İ		(electronic adj device or integrated adj		
		circuit or package or printed adj circuit adj board or printed adj wiring adj board		
		or semiconductor adj device or		
		semiconductor adj package)) and		
		(((chelat\$4) with (epta or ethylenediamine		
		or ethylenediamine or oxylate)) and		
		(immobile))		
-	945	, , , , , , , , , , , , , , , , , , ,	USPAT;	2004/09/25 16:55
		or ethylenediamine or oxylate)) and (high	US-PGPUB	
_	106	adj molecular adj weight) (((chelat\$4) with (epta or ethylenediamine	USPAT;	2004/09/26 13:16
	100	or ethylenediamine or oxylate)) and	US-PGPUB	2004/03/20 13:10
		(electronic adj device or integrated adj	00 10102	
		circuit or package or printed adj circuit		
		adj board or printed adj wiring adj board		
		or semiconductor adj device or		
		semiconductor adj package)) and		
		<pre>(((chelat\$4) with (epta or ethylenediamine or ethylenediamine or oxylate)) and (high</pre>		
		adj molecular adj weight))		
-	1239	kline.in.	USPAT	2004/09/25 17:30
-	24	kline.in. and (chelat\$4)	USPAT	2004/09/25 17:48
-	136	(integrated adj circuit) with (scratch)	USPAT;	2004/09/25 18:38
			US-PGPUB	
-	286	(integrated adj circuit) with (scratch\$4)	USPAT;	2004/09/25 18:38
_	136	//integrated add circuit/ with /comptable	US-PGPUB	2004/09/25 18:39
	120	((integrated adj circuit) with (scratch)) and ((integrated adj circuit) with	USPAT; US-PGPUB	2004/09/25 18:39
		(scratch\$4))	OD IGEOD	
	286		USPAT;	2004/09/25 18:39
		or ((integrated adj circuit) with	US-PGPUB	
		(scratch\$4))		
-	10	(((integrated adj circuit) with (scratch))	USPAT;	2004/09/25 18:40
		or ((integrated adj circuit) with	US-PGPUB	
_	0	<pre>(scratch\$4))) and chelat\$4 ("(wateradjpollutionadjmonitoring)with(chelation)</pre>	ትነ ር ታለጋያለምነ ጉኦ፣	2004/00/27 11.55
_	1	(water adj pollution adj monitoring) with (chel	USPAT).PN.	2004/09/27 11:55 2004/09/27 11:56
		(chelat\$4)	JULAI	2004/03/27 11.30
[-	1119	(analy\$6) with (chelat\$4)	USPAT	2004/09/27 11:57
-	614	((analy\$6) with (chelat\$4)) and (metal adj	USPAT	2004/09/27 11:57
		ion\$4)		

				0004/00/07 44 50
-	624	((analy\$6) with (chelat\$4)) and (metal\$4	USPAT	2004/09/27 11:58
		adj ion\$4)		
-	327	(((analy\$6) with (chelat\$4)) and (metal\$4	USPAT	2004/09/27 11:59
		adj ion\$4)) and (chelating adj agent)		
-	46	(((USPAT	2004/09/27 12:22
		adj ion\$4)) and (chelating adj agent)) and		
		((chip) or (wafer) or (ic) or (integrated		
		adj circuit) or (semiconductor adj device)		
		or (electronic adj component) or		
İ		(electroinc adj device) or (printed adj		
		circuit) or (printed adj wiring) or		į
		(circuit adj board))		
-	428	604/\$.ccls. and (chelat\$4)	USPAT	2004/09/27 13:38
-	9	(604/\$.ccls. and (chelat\$4)) and	USPAT	2004/09/27 13:44
		(integrated adj circuit or semiconductor		
	,	adj chip or integrated adj circuit)		
-	448	427/\$.ccls. and (chelating adj agent)	USPAT	2004/09/27 14:03
-	2838	427/\$.ccls. and (integrated adj circuit)	USPAT	2004/09/27 14:04
-	7174	427/\$.ccls. and (chip or wafer)	USPAT	2004/09/27 14:04
-	43	(427/\$.ccls. and (chelating adj agent))	USPAT	2004/09/27 14:57
		and (427/\$.ccls. and (chip or wafer))		
-	407	(((174/260) or (361/760)).CCLS.) and	USPAT	2004/09/27 20:42
		(encapsul\$6)		
-	297	((((174/260) or (361/760)).CCLS.) and	USPAT	2004/09/27 20:22
		(encapsul\$6)) and package		
-	109	(((174/260) or (361/760)).CCLS.) and	USPAT	2004/09/27 20:42
		(underfill)		
-	43	(((((174/260) or (361/760)).CCLS.) and	USPAT	2004/09/27 20:56
		(encapsul\$6)) and package) and		
		((((174/260) or (361/760)).CCLS.) and		
		(underfill))		